查询"2引6%间隙供应商 Effect Transistor Silicon N-Channel MOS Type (MACH II π-MOS VI)

# 2SK3936

#### **Switching Regulator Applications**

Small gate charge: Qg = 60 nC (typ.)

• Fast reverse recovery time: t<sub>rr</sub> = 380 ns (typ.)

• Low drain-source ON-resistance:  $R_{DS (ON)} = 0.2 \Omega (typ.)$ 

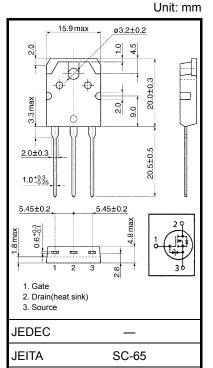
• High forward transfer admittance:  $|Y_{fS}| = 16.5 \text{ S (typ.)}$ 

Low leakage current: I<sub>DSS</sub> = 500 μA (V<sub>DS</sub> = 500 V)

• Enhancement mode:  $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$ 

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	500	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	500	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	ΙD	23	А	
	Pulse (Note 1)	I <sub>DP</sub>	92	A	
Drain power dissipation (Tc = 25°C)		P <sub>D</sub>	150	W	
Single-pulse avalanche energy (Note 2)		E <sub>AS</sub>	759	mJ	
Avalanche current		I <sub>AR</sub>	23	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	15	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



2-16C1B

Weight: 4.6 g (typ.)

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Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristic	Symbol	Max	Unit	
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.833	°C/W	
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W	

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 90 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C(initial)}$ , L = 2.44 mH,  $I_{AR} = 23 \text{ A}$ ,  $R_G = 25 \Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

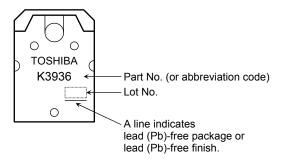
## Energy istics (Ta = 25°C)

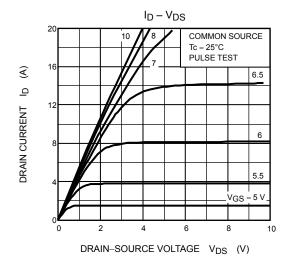
Char	acteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Gate-source breakdown voltage		V (BR) GSS	$I_D = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30	_	_	V
Drain cutoff curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	_	_	500	μА
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500	_	_	V
Gate threshold v	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source ON	-resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.5 A	_	0.2	0.25	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 11.5 A	8	16.5	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	4250	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	10	_	
Output capacitance		C <sub>oss</sub>		_	420	_	
Switching time	Rise time	t <sub>r</sub>	$\begin{array}{c c} 10 \text{ V} \\ \text{VGS} \\ 0 \text{ V} \end{array}$ $\begin{array}{c c} \text{ID} = 11.5 \text{ A} & \text{VOUT} \\ \text{O} \\ \text{A.7 } \Omega \\ \text{M} \end{array}$ $\begin{array}{c c} \text{RL} = \\ 17.4 & \Omega \end{array}$ $\begin{array}{c c} \text{VDD} \approx 200 \text{ V} \end{array}$	_	12	_	
	Turn-on time	t <sub>on</sub>		_	45	_	
	Fall time	t <sub>f</sub>		_	10	_	ns
	Turn-off time	t <sub>off</sub>	Duty ≦ 1%, t <sub>W</sub> = 10 μs	_	80	_	
Total gate charge		Qg			60		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 23 \text{ A}$	_	50	_	nC
Gate-drain charge		Q <sub>gd</sub>		_	10		

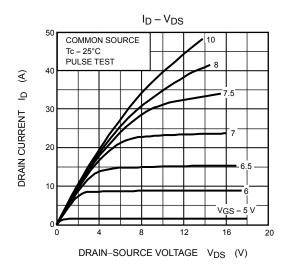
## Source-Drain Ratings and Characteristics (Ta = 25°C)

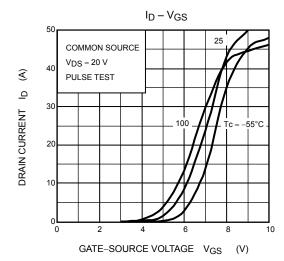
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	23	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	92	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 23 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 23 \text{ A}, V_{GS} = 0 \text{ V},$	_	380	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> /dt = 100 A/μs	_	2.4	_	μС

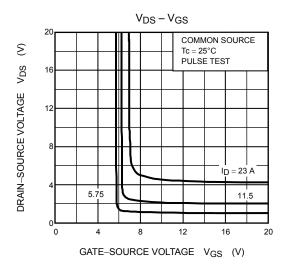
## Marking

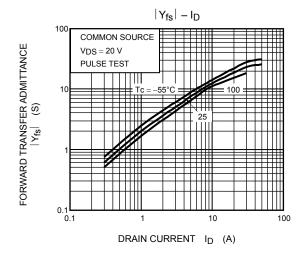


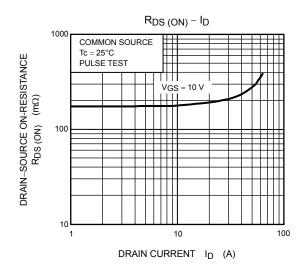


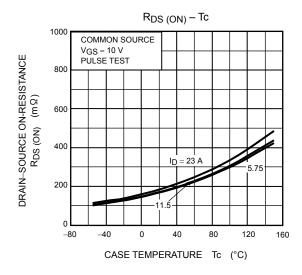


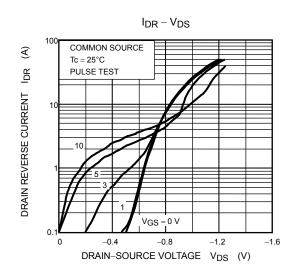


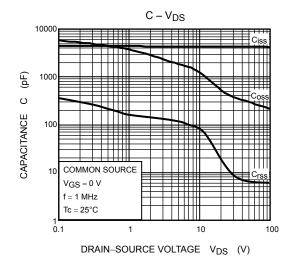


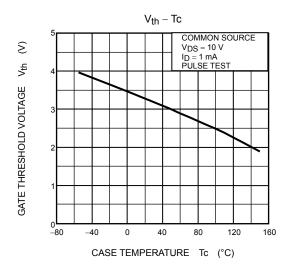


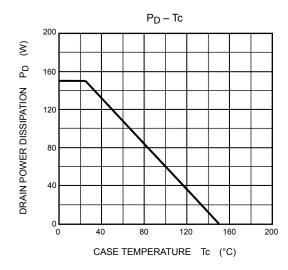


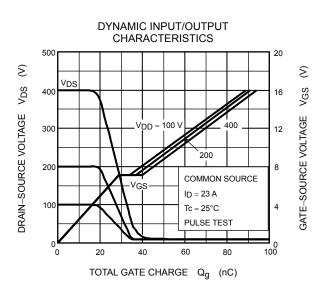


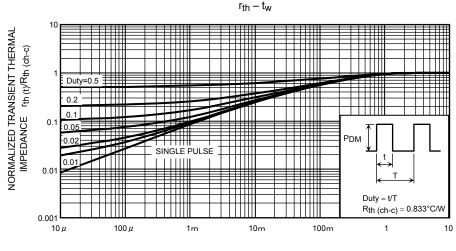




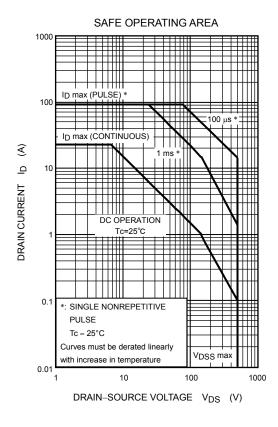


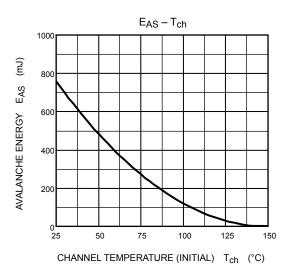


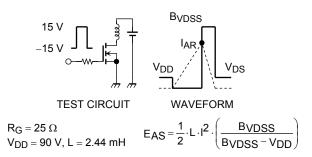




PULSE WIDTH  $t_W$  (s)







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